

[0023] FIG. 1 is a perspective view of an example product made of two wafers aligned in accordance with the techniques disclosed;

[0024] FIG. 2 is a cross-sectional, cut-away view through the example product of FIG. 1 illustrating the two wafer portions that are aligned and assembled in accordance with the techniques disclosed;

[0025] FIG. 3 is a plan view of one of the wafers used for the example product of FIG. 1;

[0026] FIG. 4 is a plan view of an example wafer with features formed on, or in a surface of the wafer that are to be aligned with another wafer by reference to the features;

[0027] FIG. 5 is a plan view of the example wafer of FIG. 4 illustrating example notching of the wafer for alignment with another wafer;

[0028] FIG. 6 is a detailed cut-away view of an example pivot-notch formed in the wafer of FIG. 5;

[0029] FIG. 7 is a detailed cut-away view of an example stop-notch formed in the wafer of FIG. 5;

[0030] FIG. 8 is a detailed cut-away view of an example bias-notch formed in the wafer of FIG. 5;

[0031] FIG. 9 is a plan view of an example two-contact element that may be used for two-point contact in the pivot-notch of the wafer of FIG. 5;

[0032] FIG. 10 is a plan view of an example single-contact element that may be used for single-point contact with the stop-notch of the wafer of FIG. 5;

[0033] FIG. 11 is a plan view of an example fixture for aligning two notched wafers;

[0034] FIG. 12 is a plan view of the example contacts and forces exerted on a notched wafer for alignment;

[0035] FIG. 13 is a diagrammatical view of an example notching station for notching a wafer to be aligned;

[0036] FIG. 14 is a diagrammatical view of an example bonding station for bonding two aligned wafers with respect to one another in an aligned orientation; and